

What is claimed is:

1. A substrate cleaning apparatus for cleaning a substrate while rotating the substrate and placing a cleaning member in contact with the rotating substrate,
5 comprising:

a self-cleaning member mounted to an arm supporting the cleaning member, the self-cleaning member being configured to come into contact with the cleaning member to perform self-cleaning of the cleaning member; and

a moving mechanism mounted to the arm supporting the cleaning member, the
10 moving mechanism being configured to move, during cleaning of the substrate, the self-cleaning member between a position where the self-cleaning member is in contact with the cleaning member and a position where the self-cleaning member is separated from the cleaning member.

15 2. The substrate cleaning apparatus according to claim 1, wherein the cleaning member comprises a roll sponge.

3. The substrate cleaning apparatus according to claim 1, wherein the self-cleaning member is mounted to the arm via a mounting member.

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4. The substrate cleaning apparatus according to claim 1, wherein the self-cleaning member is mounted to the moving mechanism which is mounted to the arm.

25 5. The substrate cleaning apparatus according to claim 1, wherein the self-cleaning member comprises a cleaning plate.

6. The substrate cleaning apparatus according to claim 1, wherein the moving mechanism comprises a linear moving mechanism or a rotational moving mechanism.

7. The substrate cleaning apparatus according to claim 1, wherein the moving mechanism is housed in a waterproof housing having a hole that allows movement of a moving portion of the moving mechanism.

5 8. The substrate cleaning apparatus according to claim 7, wherein a bellows is provided so as to surround the hole of the housing and the moving portion of the moving mechanism.

 9. The substrate cleaning apparatus according to claim 1, further comprising a
10 nozzle mounted to the arm supporting the cleaning member and configured to supply a cleaning liquid to an area of contact between the cleaning member and the self-cleaning member.

 10. A substrate processing apparatus comprising:
15 a substrate processing section for performing predetermined processing of a substrate; and

 a substrate cleaning apparatus for cleaning the substrate which has undergone the predetermined processing in the substrate processing section, the substrate cleaning apparatus comprising a substrate cleaning apparatus according to claim 1.

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 11. The substrate processing apparatus according to claim 10, wherein the substrate processing section is a polishing section for polishing the substrate.

 12. A substrate cleaning method comprising:
 cleaning a substrate while rotating the substrate and placing a cleaning member
25 in contact with the rotating substrate; and

 self-cleaning the cleaning member by actuating a moving mechanism and bringing a self-cleaning member into contact with the cleaning member while cleaning the substrate,

wherein the moving mechanism is configured to move, during cleaning of the substrate, the self-cleaning member between a position where the self-cleaning member is in contact with the cleaning member and a position where the self-cleaning member is separated from the cleaning member.

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13. The substrate cleaning method according to claim 12, further comprising:
moving the cleaning member away from the substrate and moving the cleaning member to a standby position after cleaning of the substrate; and
self-cleaning the cleaning member by bringing the self-cleaning member into
10 contact with the cleaning member on standby in the standby position.

14. The substrate cleaning method according to claim 12, wherein a cleaning liquid can be supplied to an area of contact between the cleaning member and the self-cleaning member during said self-cleaning of the cleaning member.

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